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**PATENT** 

## IN THE UNATED STATES PATENT AND TRADEMARK OFFICE

Applicant:

Qing Ma

**Examiner: Roy Potter** 

Serial No.:

10/774,923

Group Art Unit: 2822

Filed:

February 9, 2004

Docket No: 884.803US2

Title

DIRECT BUILD-UP LAYER ON AN ENCAPSULATED DIE PACKAGE

TER ON AN ENCAPSULATED DIE 1.

HAVING A MOISTURE BARRIER STRUCTURE

Assignee:

**Intel Corporation** 

Customer Number: 21186

## PETITION FOR A ONE-MONTH EXTENSION OF TIME

MS AF Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

In accordance with the provision of 37 CFR § 1.136(a), it is respectfully requested that a one-month extension of time be granted in which to respond to the Final Office Action mailed October 6, 2005, said period of response being extended from January 6, 2006 to February 6, 2006.

Please charge Deposit Account No. 19-0743 in the amount of \$120.00 to cover the required extension fee. Please charge any additional fees or credit overpayment to deposit Account No. 19-0743.

Respectfully Submitted

QING MA

By her Representatives,

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.

Attorneys for Intel Corporation

P.O. Box 2938

Minneapolis, Minnesota 55402

(612) 349-9592

Date: Feb. 4 2006	By: Unn M. McCacken	
	Ann M. McCrackin	
	Reg. No. 42 858	

CERTIFICATE UNDER 37 CFR § 1.8: The undersigned hereby cert	tifies that th	is corres	pondence is being	deposited with the	United States
Postal Service with sufficient postage as first class mail, in an envelo				r for Patents, P.O.	Box 1450,
Alexandria, VA 22313-1450, on this 6th day of February 2006.	$\triangle$	ıΛ	1		

Name:	Chris Hammond	Signature: (No HOLLAN MON CO)